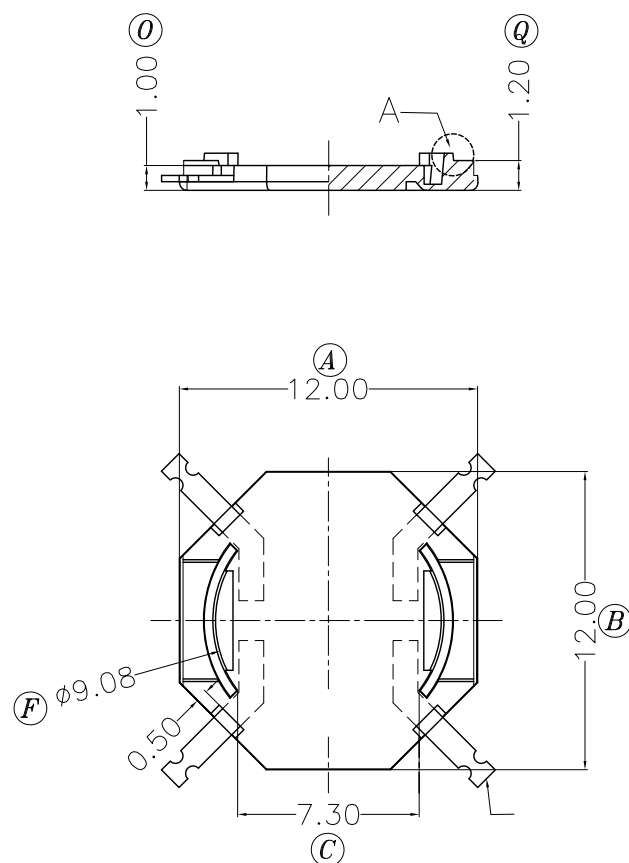


A: amplify (5:1)

Remark:

1. slodering requirement:
withstand the 260° C reflow soldering
process of PAD(260° , 3-5s, 3times)

REV.	REVISIONS	REC.	DATE	REV.	REVISIONS	REC.	DATE
0	First Issue		2013.08.02	3	Add a step on the terminal		2014.05.12
1	Change the "C" from 5.50 to 7.30		2013.10.24				
2	Add the PAD area size and plating requirement		2013.10.29				

DRAWN & DRAFTED BY	XING JY	TOLERANCES	ANGLE:	TITLE:
CHECKED & APPROVED BY	BEN LEE	0<L≤4 ±0.1 4<L≤16 ±0.2 16<L≤63 ±0.3	±1°	SMD BASE DRH124 4PAD
		COPLANARITY 0.1mm MAX	UNIT: MM	PLASTIC MATERIAL: LCP
			ORIGIN: GZ	METAL MATERIAL: PHOSPHOR BRONZE
				PIN TENSION LOAD: 1.0Kg
				DATE: 2014.05.12
				DRAWING NO. ST-BS058.01
				REV. 3



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